/ Descriptions

PDFN5×6 N

N-Channel MOSFET in a PDFN5×6 Plastic Package .

/ Features

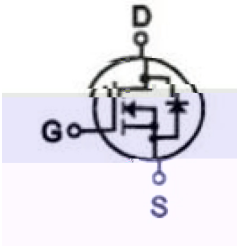
Low $R_{DS(ON)}$ to minimize conductive loss;low Gate Charge for fast switching;Low Thermal resistance;HF Product.

/ Applications

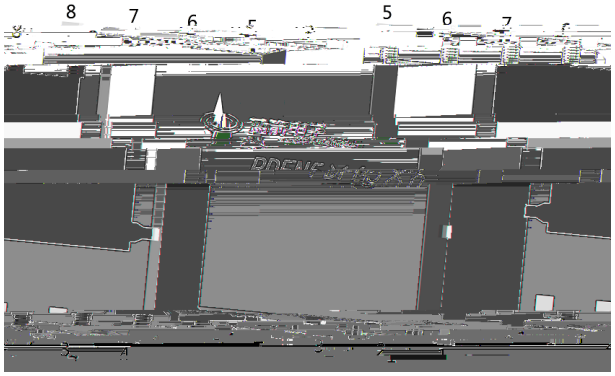
MB/NB/UMPC/VGA Buck -

Battery Management,High Frequency Point-of-Load Synchronous Buck Conventer for MB/NB/UMPC/VGA,Networking DC-DC Power System,Load Switch.

/ Equivalent Circuit



/ Pinning



PIN1 2 3 S PIN4 G PIN5 6 7 8 D

Pin	极性
1	S
2	S
3	S
4	G
5	D
6	D

/ Marking

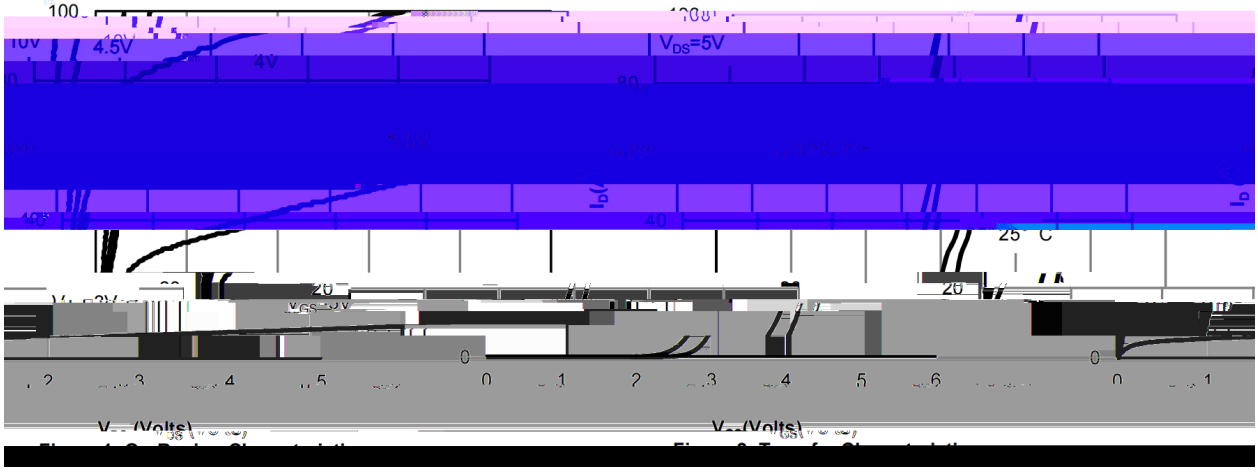
See Marking Instructions.

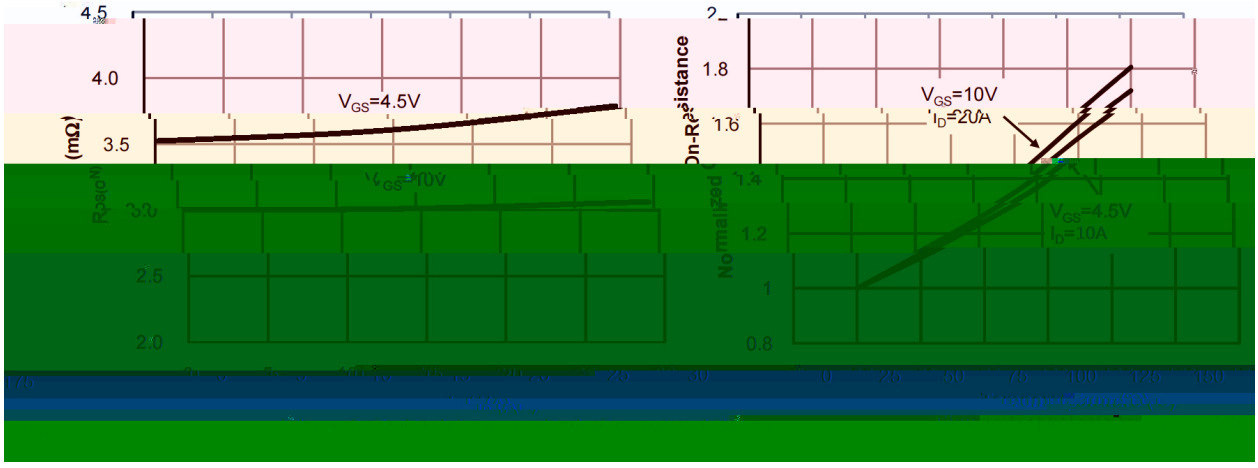
Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DS}	60	V
Continuous Drain Current	I_D	111	A
Pulsed Drain Current	I_{DM}	227	A
Gate-Source Voltage	V_{GS}	± 20	V
Power Dissipation	$P_D(T_c=25$)	78	W
Avalanche energy(L=0.5mH)	E_{AS}	2000	mJ
Avalanche Current(L=0.5mH)	I_{AS}	47	A
Junction and Storage Temperatur	TJ5ane		

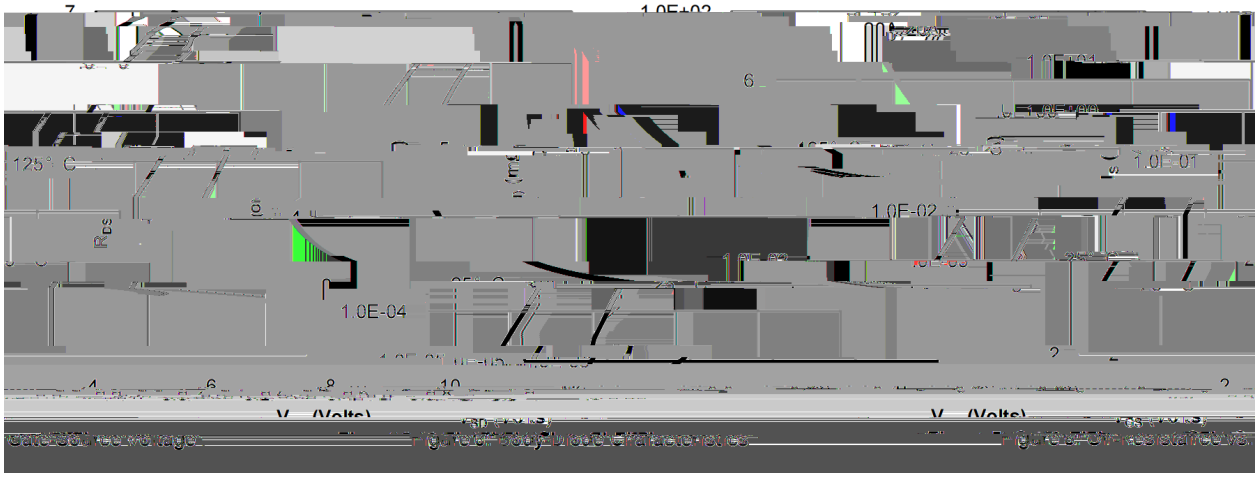
/ Electrical Characteristics(Ta=25)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Turn-On Delay Time	$t_{d(on)}$	V_{GS}=10V V_{DS}=30V R_L=1.5Ω R_{GEN}=3Ω		13		ns
Turn-On Rise Time	t_r			4		
Turn-Off Delay Time	$t_{d(off)}$			47		
Turn-Off Fall Time	t_f			6.5		

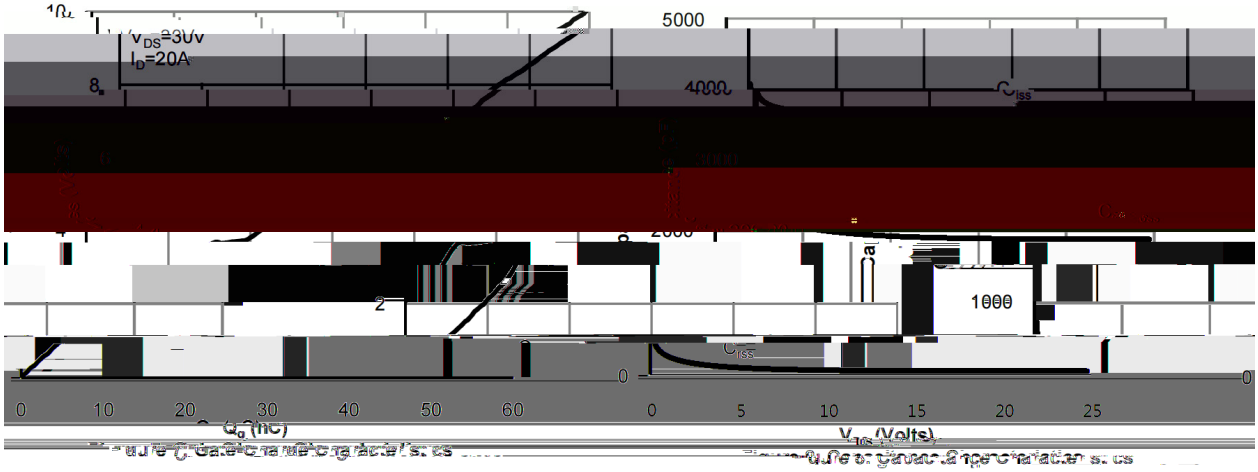
/ Electrical Characteristic Curve

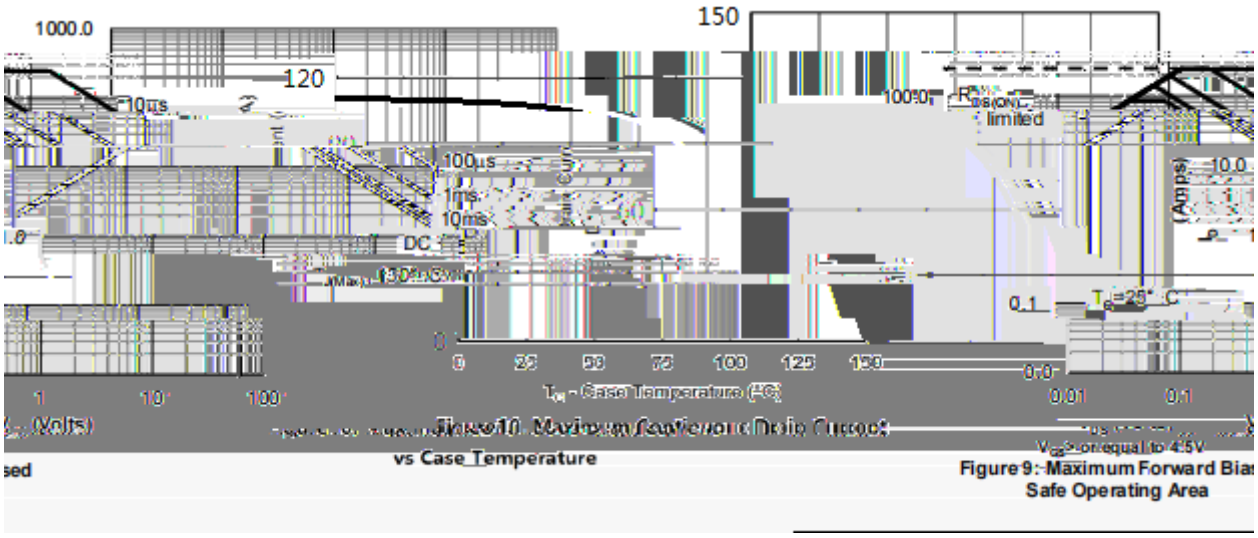






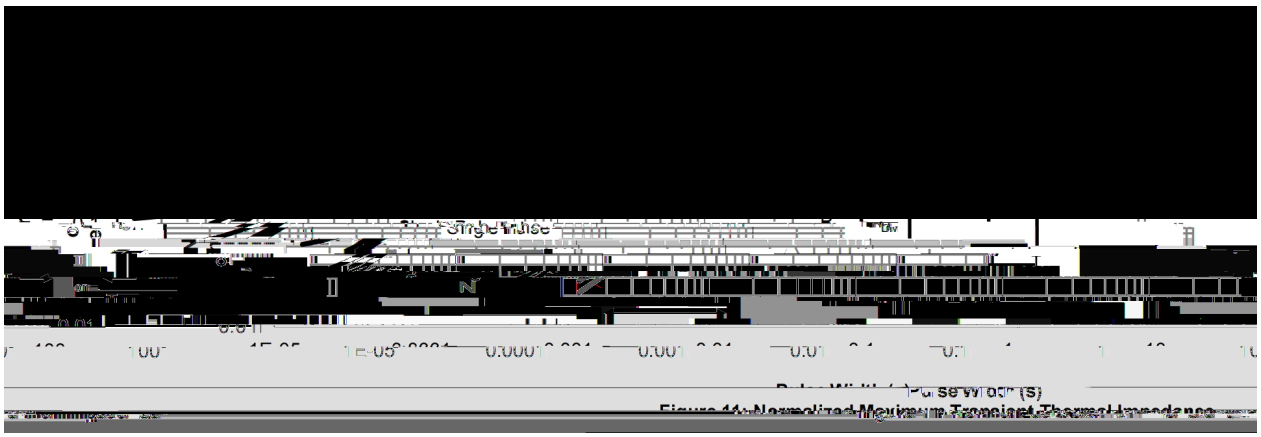
/ Electrical Characteristic Curve





vs Case Temperature

Figure 9: Maximum Forward Bias Safe Operating Area



/ Package Dimensions

/ Marking Instructions

BR

035N06S

****

Note

BR	Company Code
035N06S	Product Type Code
****:	Lot No. Code, code change with Lot No

( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)

		Note:
1	150 180 60 90sec;	1.Preheating:150~180 , Time:60~90sec.
2	245±5 5±0.5sec;	2.Peak Temp.:245±5 , Duration:5±0.5sec.
3	2 10 /sec.	3. Cooling Speed: 2~10 /sec.

/ Resistance to Soldering Heat Test Conditions

260±5	10±1 sec.	Temp.:260±5	Time:10±1 sec